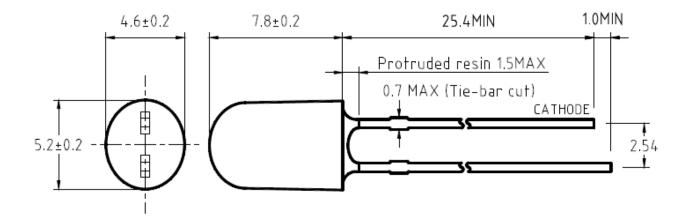


# SPECIFICATIONS CLV54SY2D-70

# **OUTLINES DIMENSIONS / Lamps without Standoffs**



### Notes:

- 1. All Dimensions are in millermeters (inches).
- 2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwise noted.
- 3. Specification are subject to change without notice.

### **Luminous Intensity Bin Table**

IF=20mA

Rank name	Min (mcd)	Max (mcd)
T	2500	3200
$\mathbf{U}$	3200	4200
V	4200	5500

<sup>\*</sup> Tolerance for each bin limit is ±15%

### **Color Bin Table**

### IF=20mA

Rank name	Min (nm)	Max (nm)
1	585	587.5
2	587.5	590
3	590	592.5
4	592.5	595

<sup>\*</sup> Iolerance for each bin limit is ± 1nm

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLV54SY2D-70	AllnGaP	Yellow	Yellow Diffused	70/35°



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	P <sub>D</sub>	120	mW
Peak Forward Current (1/10 Duty Cycle @1KHz)	I <sub>PF</sub>	100	mA
Continuous Forward Current	l <sub>F</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature Range	T <sub>OPR</sub>	-30~+85	°C
Storage Temperature Range	T <sub>STG</sub>	-40~+100	°C

Solder temperature 1.6 mm from body for 5 seconds at 260°C

# **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	Iv	I <sub>F</sub> = 20mA	2500	3000		mcd
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA		2.1	2.4	V
Reverse Current	<b>I</b> <sub>R</sub>	V <sub>R</sub> = 5V			50	uA
Peak Wavelength	λР	I <sub>F</sub> = 20mA		593		nm
Dominant Wavelength	λь	I <sub>F</sub> = 20mA	585	590	595	nm
Spectrum Radiation Bandwidth	Δλ	I <sub>F</sub> = 20mA		15		nm

<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.



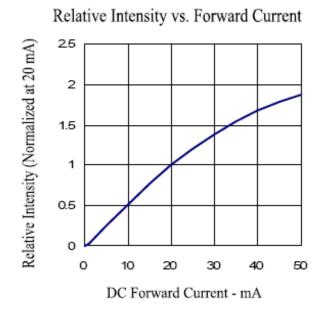
ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

<sup>\*</sup>IFP = Pulse Width ≤ 10ms, Duty Ratio ≤ 1/10

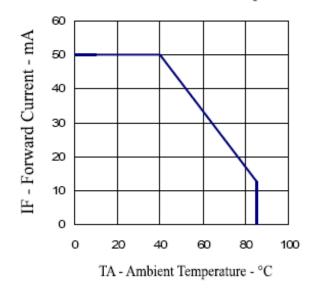


# **OPTICAL CHARACTERISTIC CURVES**

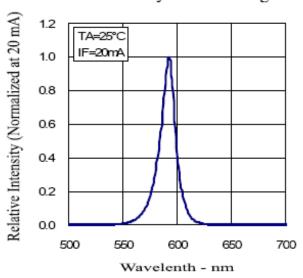
# Forward Current vs. Forward Voltage 50.0 40.0 30.0 10.0 1.0 1.5 20.0 VF - Forward Voltage - V



# Forward Current vs. Ambient Temperature



## Relative Intensity vs. Wavelength





ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



### **SOLDERING CONDITIONS – LAMP TYPE LED**

- \* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- \* Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
	3mm Series	Others		
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy		

- \* Do not apply any stress to the lead. Particularly when heated.
- \* The LED must not be repositioned after soldering.
- \* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- \* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- \* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

